L Number	Hits	Search Text	DB	Time stamp
1	2	"20010009803"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/15 18:18
2	1048	via near12 mu	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/15 18:31
3	3	(via near12 mu) and damascene	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/15 18:40
5	56062	(ang angstrom nm nanometer) near12 (opening hole groove trench via dielectric insulation insulating insulator ILD)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/15 18:38
6	34310	(micron mu) near12 (opening hole groove trench via dielectric insulation insulating insulator ILD)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/15 18:38
7	85504	((ang angstrom nm nanometer) near12 (opening hole groove trench via dielectric insulation insulating insulator ILD)) ((micron mu) near12 (opening hole groove trench via dielectric insulation insulating insulator ILD))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/15 18:38
8	8190	(((ang angstrom nm nanometer) near12 (opening hole groove trench via dielectric insulation insulating insulator ILD)) ((micron mu) near12 (opening hole groove trench via dielectric insulation insulating insulator ILD))) and (((inlain inlaid fill$4) near3 (metal metallization copper aluminum Al Cu)) or damascene)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/15 18:39
9	6410	((((ang angstrom nm nanometer) near12 (opening hole groove trench via dielectric insulation insulating insulator ILD)) ((micron mu) near12 (opening hole groove trench via dielectric insulation insulating insulator ILD))) and (((inlain inlaid fill$4) near3 (metal metallization copper aluminum Al Cu)) or damascene)) and (257/$ or 438/$).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/15 18:41
10	3863	(((ang angstrom nm nanometer) near12 (opening hole groove trench via dielectric insulation insulating insulator ILD)) ((micron mu) near12 (opening hole groove trench via dielectric insulation insulating insulator ILD))) and damascene	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/15 18:41
11	3393	((((ang angstrom nm nanometer) near12 (opening hole groove trench via dielectric insulation insulating insulator ILD)) ((micron mu) near12 (opening hole groove trench via dielectric insulation insulating insulator ILD))) and damascene) and (257/$ or 438/$).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/15 18:41
12	2376	(((ang angstrom nm nanometer) near12 (opening hole groove trench via dielectric insulation insulating insulator ILD)) ((micron mu) near12 (opening hole groove trench via dielectric insulation insulating insulator ILD))) and (dual adj damascene)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/15 19:29
13	402	((((ang angstrom nm nanometer) near12 (opening hole groove trench via dielectric insulation insulating insulator ILD)) ((micron mu) near12 (opening hole groove trench via dielectric insulation insulating insulator ILD))) and (dual adj damascene)) and @ad<19990630	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/15 18:43

14	257	((((ang angstrom nm nanometer) near12 (opening hole groove trench via dielectric insulation insulating insulator ILD)) ((micron mu) near12 (opening hole groove trench via dielectric insulation insulating insulator ILD))) and (dual adj damascene)) and @rlad<19990630	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/15 18:43
15	595	(((((ang angstrom nm nanometer) near12 (opening hole groove trench via dielectric insulation insulating insulator ILD)) ((micron mu) near12 (opening hole groove trench via dielectric insulation insulating insulator ILD))) and (dual adj damascene)) and @ad<19990630) (((((ang angstrom nm nanometer) near12 (opening hole groove trench via dielectric insulation insulating insulator ILD)) ((micron mu) near12 (opening hole groove trench via dielectric insulation insulating insulator ILD))) and (dual adj damascene)) and @rlad<19990630)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/15 19:26
16	0	" .mu."	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/15 19:26
17	16292	$3mu near12 (opening hole groove trench via dielectric insulation insulating insulator ILD)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/15 19:27
18	26	($3mu near12 (opening hole groove trench via dielectric insulation insulating insulator ILD)) and (dual adj damascene)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/15 19:30